



电性参数

典型特性曲线

可靠性实验

外形尺寸

包装

焊接指导

使用注意事項

Doc. No. : X





Reliability Test Items And Conditions

Description	Item	Test criterion	Test condition	Test time	Qty
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GIJ



Packaging (1)

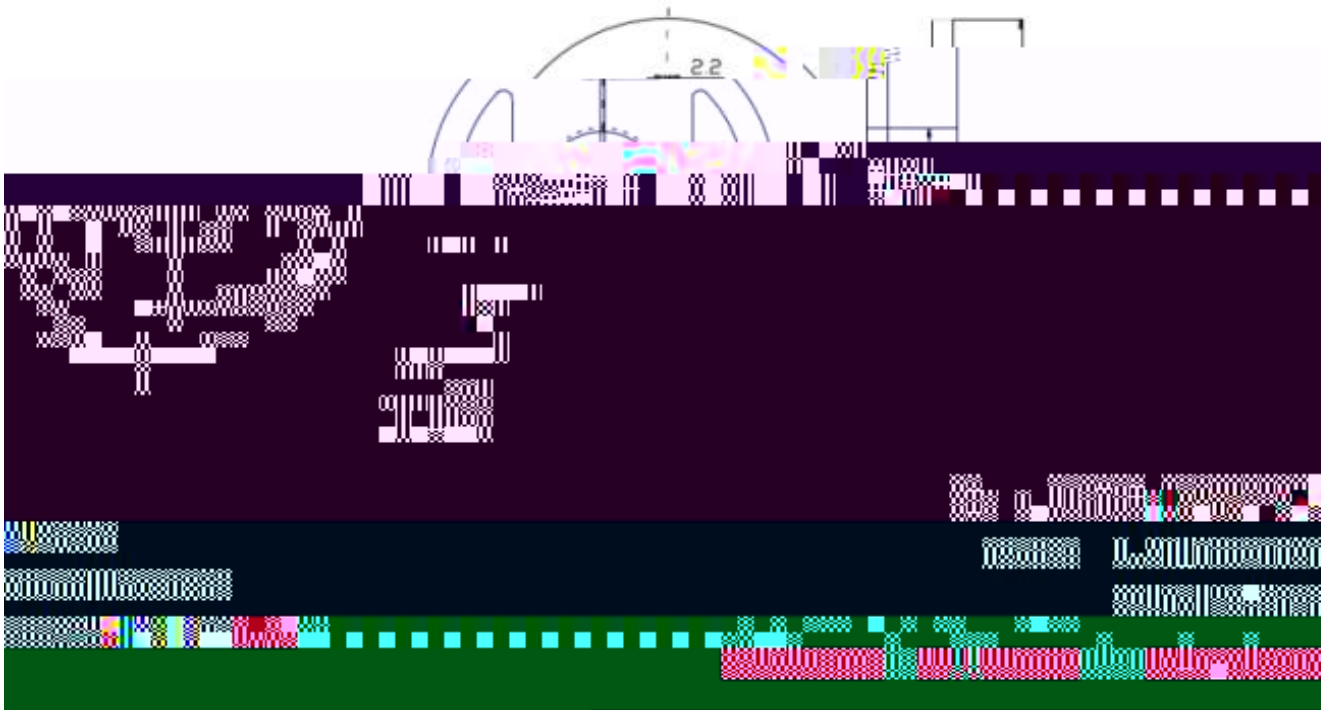


圖 磁及載帶卷出方向及空穴規格 Disk and carrier belt direction of hole









使用注意事项 (2)

Precautions (2)

建议

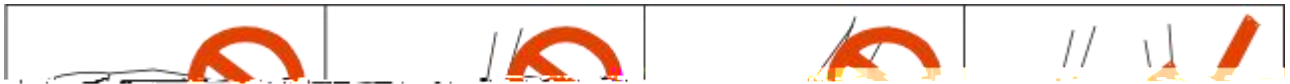
In designing a circuit, the current through each LED must not exceed the absolute maximum rating specified

使用注意事项 (3)

Precautions (3)

其他事项

When handling the product, touching the encapsulant with bare hands will not only contaminate its surface, but also affect on its optical characteristics. Excessive force to the encapsulant might result in catastrophic failure of the LEDs due to die breakage or wire deformation. For this reason, please do not put excessive stress on LEDs, especially when the LEDs are heated such as during Reflow Soldering.



LED

The epoxy resin of encapsulant is fragile, so please avoid scratch or friction over the epoxy resin surface. While handling the product with tweezers, do not hold by the epoxy resin, be careful.

眼睛保护忠告:

LED

LED

Viewing direct to the light emitting center of the LEDs, especially those of great Luminous Intensity, will cause great hazard to human eyes. Please be careful.

If there are any modifications to the specification sheet, no further notice will be given